

Thick Film Chip Resistor (General)



Chip resistors, which are available for surface mounting, are general passive component which is useful for voltage drop, current controlling in circuit and surface mounting is available.

Samsung electro-mechanics also manufactures a wide range of chip resistors such as general, precision, trimmable and low ohms and so on.Production is increasing with demand for small size & light weight of set product. We provide ultra-small, high-reliability, high-stability resistors. We have obtained ISO-9002/QS-9000 and ISO-14001 certification.

General Features

- Very small, thin, and light weight.

- Both flow and reflow soldering are applicable.
- Owing to the reduced lead inductance, the high frequency characteristic is excellent.
- Suitable size and packaging for surface mount assembly.

Applications

- General purpose.
 - Home Appliances.
 - (DVD, Digital TV, Camcorder, VTR, Digital Camera, Audio, Tuner).
 - For Computers & Communication Device.

(Notebook, Memory Module, Mobile, Network Equipment, etc)

Part Numbering



1 CODE DESIGNATION

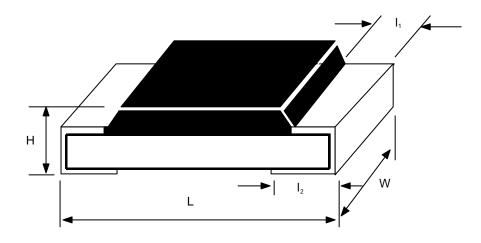
RC : This code expresses the Resistor that is produced by Samsung Electro-Mechanics CO.,LTD.



2 DIMENSION

The dimension is expressed as 4 digits number by SI unit (mm). <Table 1> Left 2 digits are length of resistor, and the other 2 digits are width. <Fig 1>

<Fig 1>



<Table 1>

[Unit : mm]

Dimension	※0402	0603	1005	1608	2012	3216	3225	5025	6432
(inch)	(01005)	(0201)	(0402)	(0603)	(0805)	(1206)	(1210)	(2010)	(2512)
L	0.40±0.02	0.60±0.03	1.00±0.05	1.60±0.10	2.00±0.20	3.20±0.20	3.20±0.20	5.00±0.20	6.30±0.20
W	0.20±0.02	0.30±0.03	0.50±0.05	0.80±0.15	1.25±0.15	1.60±0.15	2.55±0.20	2.50±0.20	3.20±0.20
Н	0.12±0.02	0.23±0.03	0.35±0.05	0.45±0.10	0.50±0.10	0.55±0.10	0.55±0.10	0.55±0.10	0.55±0.10
I ₁	0.10±0.03	0.10±0.05	0.20±0.10	0.30±0.20	0.40±0.20	0.45±0.20	0.45±0.20	0.60±0.20	0.60±0.20
I 2	0.10±0.03	0.15±0.05	0.25±0.10	0.35±0.10	0.35±0.20	0.40±0.20	0.40±0.20	0.60±0.20	0.60±0.20

% New : under developing('08)

③ RESISTANCE TOLERANCE

The Resistance Tolerance is expressed as 1 digit alphabet by EIAJ standard. <Table 2>

<Table 2>

item	G	J	К	М
Tolerance (%)	± 2	± 5	± 10	± 20
Producing Series	E-48	E-24	E-12	E-6



O NOMINAL RESISTANCE VALUE

The Nominal Resistance Value is expressed as 3 or 4 digits based on EIAJ standard. <Table 3>

<Table 3>

item	3 digits mark(E-24)	4 digits mark(E-48)
Resistance Tolerance	G, J, K, M	G
Only number	First 2 digits : Resistance value Last 1 digit : Exponential number of 10.	First 3 digits : Resistance value Last 1 digit : Exponential number of 10.
Number & alphabet "R"	Read alphabet "R" as decimal point.	Read alphabet "R" as decimal point.
Example	 1) 101 : 10 × 10¹ = 10 × 10 = 100Ω 2) 7R5 : 7 . 5 = 7.5 Ω 3) R75 : 0.75 Ω 	1) 1001 : 100 × 10 ¹ = 100 × 10 = 1 $k\Omega$ 2) 9R09 : 9.09 = 9.09 Ω

If resistance value in E-96 is same resistance value in E-24, we mark 3 or 4 digits..

In case of JUMPER(0 ohm), '000' is marked on that resistor.

* 0603, 1005, 1608 (4 digits mark) : No Marking on the resistor.

O PACKAGING CODE

The Packaging Code is expressed as 2 digits alphabet. <Table 4>

<table 4=""></table>	•
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Packaging Code	Description	Dimension	Packaging Q'ty
		0603	15,000 PCS
6.6		1005	10,000 PCS
CS	7" REEL PACKAGING	1608, 2012, 3216, 3225	5,000 PCS
		5025, 6432	4,000 PCS
ES	10" REEL PACKAGING	1005	30,000 PCS
E 3	IO REEL PACKAGING	1608, 2012, 3216, 3225	10,000 PCS
		1005	40,000 PCS
A S	13" REEL PACKAGING	1608, 2012, 3216, 3225	20,000 PCS
		5025, 6432	15,000 PCS
		1608	25,000 PCS
G S	BULK CASE PACKAGING	2012	10,000 PCS
		3216	5,000 PCS



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CHARACTERISTIC LINE UP

RESISTANCE RANGE

The Resistance Range that we produce depends on the Dimension and the Resistance Tolerance of the resistor. <Table 16>

<Table 16>

[unit : Ω]

Dim. (inch) Tol.	*0402 (01005)	0603 (0201)	1005 (0402)	1608 (0603)	2012 (0805)	3216 (1206)	3225 (1210)	5025 (2010)	6432 (2512)	Туре
G	10~1M	10~1M	10 ~1M	1 ~1M	1 ~1M	1~1M	1~1M	1~1M	1~1M	G
J	10~1M	1~10M	G							
	_	1~10M	G							
K	_	-	-	1~10M	1~10M	1~10M	1~10M	1~10M	1~10M	т
М	_	_	-	1~10M	1~10M	1~10M	1~10M	1~10M	1~10M	Т

* New : under developing ('08)

* Type Representation : G(General), T(Trimmable)



RATED POWER

The Rated Power is classified by the dimension of the resistor. <Table 17>

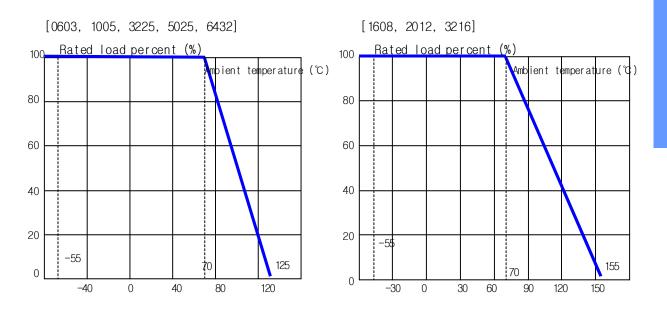
<Table 17>

Dimension	0603	1005	1608	2012	3216	3225	5025	6432
item	(0201)	(0402)	(0603)	(0805)	(1206)	(1210)	(2010)	(2512)
Rated Power	1/20 W (0.05 W)	1/16 W (0.063 W)	1/10 W (0.100 W)	1/8 W (0.125 W)	1/4 W (0.25 W)	1/3 W (0.33 W)	2/3 W (0.67W)	1.0 W
Working Volt(Max)	25 V	50 V	50 V	150 V	200 V	200 V	200 V	200 V
STOL, IOL Volt.(Max)	50 V	100 V	100 V	300 V	400 V	400 V	400 V	400 V

STOL : Short Time OverLoad IOL : Intermittent OverLoad

* The rated power is specified as continuous full loading power at the ambient temperature of 70 ± 2 °C. In case of the temperature exceeding 70 ± 2 °C, the power should be derated in accordance to <Fig 17>.

<Fig 17>.



- Working Temperature
 - 55 $^\circ\!\!{\rm C}~\sim$ + 125 $^\circ\!\!{\rm C}$: 0603, 1005, 3225, 5025, 6432

- 55 $^\circ\!\! C~\sim$ + 155 $^\circ\!\! C$: 1608, 2012, 3216



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RELIABILITY TEST CONDITION

Jumper's reliability test data are only applied to General type resistor.

ELECTRICAL CHARACTERISTIC

The electrical characteristic test should satisfy the test method, procedure, and standard.

If there is no special comment, Each test performs in standard state.

(temperature 20°C, humidity 65%RH, pressure 1023mbar)

ito m	Permissible devi	ation	Took mathed
item	Resistor	Jumper	Test method
DC resistance	DC resistance value should be within the specified resistance tolerance.	50mΩ Maximum	$\begin{array}{r llllllllllllllllllllllllllllllllllll$
Temperature Coefficient of Resistance	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	-	• Standard : JIS C 5201-1 4.8 • Temp. : $20^{\circ}C \rightarrow -55^{\circ}C \rightarrow 20^{\circ}C \rightarrow 125^{\circ}C \rightarrow 20^{\circ}C$ • Test board : <fig 13=""> • Calculation : TCR(ppm/°C) = $\frac{R-R_0}{R_0} \times \frac{1}{T-T_0} \times 10^6$ To : $20 \pm 2^{\circ}C$ R_0 : Resistance at T₀ (Ω) T : Test temperature (-55, 125°C) R : Resistance at T (Ω)</fig>
Short time overload (STOL)	 No mechanical damage ⊿R should be within ±(1%+0.1Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.13 Test voltage : 2.5 times of rated voltage Max. surge current at the Jumper. Applying time : 5 seconds Test board : <fig 12=""></fig>
Intermittent overload (IOL)	 No mechanical damage ⊿R should be within ±(3%+0.1Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.13 Test voltage : 2.5 times of rated voltage Max. surge current at the Jumper. Test method : 1 sec ON, 25 sec OFF 10,000⁺⁴⁰⁰cycles Test board : <fig 12=""></fig>



item	Permissible devia	ition	Test method	
nem	Resistor	Jumper	Test method	
Withstanding voltage	 No mechanical damage, short circuit, or disconnection. 	Same as left	 Standard : JIS C 5201-1 4.7 Test voltage : 0603 AC 50V 1005,1608 AC 100V, others AC 500V Applying time : 60 +10/-0 seconds Test board : <fig 13=""></fig> 	
Insulation resistance	 Should have more than 1,000MΩ 	Same as left	 Standard : JIS C 5201- 4.7 Test voltage : 0603 DC 50V 1005,1608 DC 100V, others DC 500V Applying time : 60 seconds Test pressure : 1.0±0.2 N Test board : <fig 13=""></fig> 	
Noise	$\begin{tabular}{ c c c c c } \hline $Voise standard \\ \hline $Range (9) & dB Max. \\ \hline $1 \le R < 100 & -10 \\ \hline $100 \le R < 1K & 0 \\ \hline $100 \le R < 1K & 0 \\ \hline $100 \le R < 100 K & 15 \\ \hline $100 K \le R < 10 M & 20 \\ \hline $1M \le R < 10M & 30 \\ \hline \end{tabular}$	-	 Measure equipment : QUAN-TECH NOISE METER (MODEL 315C) 	

MECHANICAL CHARACTERISTIC

The mechanical characteristic test should satisfy the test method, procedure, and standard. If there is no special comment, each test is performed at standard conditions. (temperature 20°C, humidity 65%RH, pressure 1023mbar)

item	Permissible deviation Resistor Jumper		Test method
nem			rest method
Solderability	 New solder coated more than 95% of termination 	Same as left	• Standard : JIS C 5201-1 4.17 • Test temperature : 245 \pm 5 $^\circ$ • Test time : 3 \pm 0.5 sec (dipping both side)
Bending strength	 No mechanical damage ⊿R should be within ±(0.5%+0.05Ω) 0603:±(1.0%+0.1%) 	Same as left	 Standard : JIS C 5201-1 4.33 Test board : <fig 12=""></fig> Test speed : 100mm/min Test procedure : press until 3mm, then keep 5 seconds <fig 14=""></fig> <fig 14=""></fig>



item	Permissible devia	tion	Test method	
nem	Resistor	Jumper	rest method	
Termination strength	 No mechanical damage, or sign of disconnection 	Same as left	 Standard : JIS C 5201-1 4.16 Test time : applying pressure for 5 seconds Test tension : 0603,1005,1608 - 3N (300g · f) Others (500g · f) 	
Withstanding soldering heat	 No mechanical damage ⊿R should be within ±(1%+0.05Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.18 Temperature : 260 ± 5℃ Test time : 10 ± 1second (both side dipping) Test procedure : measures after 24 hours 	
Vibration	 No mechanical damage ⊿R should be within ±(1%+0.05Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.22 Test amplitude : 1.5mm Test procedure : frequency 10Hz - 55Hz - 10Hz each 2 hours in x, y, z direction. 	

ENVIRONMENTAL CHARACTERISTIC

The Environmental characteristic test should satisfy the test method, procedure, and standard. If there is no special comment, Each test performs in standard state.

(temperature 20°C, humidity 65%RH, pressure 1023mbar)

item	Permissible devia	ition	Test method		
nem	Resistor	Jumper	rest method		
Temperature cycle	 No mechanical damage ⊿R should be within ±(1%+0.1Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.19 Test procedure : <table 11=""></table> Measure : after 100 cycles of procedure Test board : <fig 11=""></fig> <table 11=""></table> item 1 2 3 4 temp(C) -55±2 5~35 temp(C) -55±2 5~35 		
Moisture resistance life	1. No mechanical damage 2. ⊿R should be within <table 12=""> <table 12=""> <table 12=""> Range(Ω) ⊿R MAX 1 ≤ R < 10</table></table></table>	50mΩ Maximum	 Standard : JIS C 5201-1 4.14 Test condition : temp 40 ± 2°C, humid 90 ~ 95%RH Test voltage : rated voltage Test time : repeat 90min ON, 30min OFF during 1000⁻⁴⁸ hours Test board : <fig 11=""></fig> 		



itom	Permissible devia	ition	Test method	
item	Resistor	Jumper	Test method	
Low temperature exposure	 No mechanical damage ∠R should be within ±(3%+0.1Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.23 Test temperature : -55 ± 2℃ Test time : 1000⁴⁸ hours (without load) Measure : after 1 hour Test board : <fig 11=""></fig> 	
High temperature exposure	 No mechanical damage ⊿R should be within ±(3%+0.1Ω) 	50mΩ Maximum	 Standard : JIS C 5201-1 4.23 Test temperature : 1608,2012,3216 155±2℃, Others 125 ± 2℃ Test time : 1000⁴⁸ hours (without load) Measure : after 1 hour Test board : <fig 11=""></fig> 	
Load life	1. No mechanical damage2. $\trace{D}R$ should be within <table 13=""><table 13=""><table 13="">Range($\trace{\Omega}$)$\trace{L}AR$ MAX$\trace{L}1 \leq R < 10$$\trace{L}1 \leq R < 10$$\trace{L}2 \leq R < 10$</table></table></table>	50mΩ Maximum	 Standard : JIS C 5201-1 4.25 Test temperature : 70 ± 2℃ Test voltage : rated voltage Test time : repeat 90min ON, 30min OFF during 1000⁴⁸ hours Test board : <fig 11="">.</fig> 	

TEST BOARD AND SPECIFICATION

- Soldering (for lead free type)
 - > The resistor should be fixed on PCB(printed circuit board) for testing.
 - Soldering specification : JIS C 5201-1 4.18
 - * Soldering method : Flow type (Dipping type)
 - * Solder : Sn -3.0 Ag -0.5 Cu
 - * FLUX : ROSIN 25WT% (JIS K 5902), IPA 75WT% (JIS K 5901)
 - Flow soldering condition
 - * FLUX dipping time $: 5 \sim 10$ sec
 - * Pre-treatment : None
 - * Soldering temp : 260 $^\circ\!\!\mathrm{C}\pm5\,^\circ\!\!\mathrm{C}$
 - * Soldering time : 10 ± 1 sec

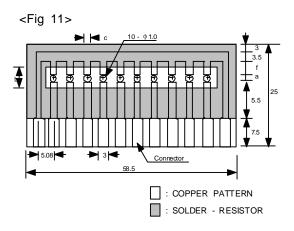


Test board

▷ Test board

<table 1<="" th=""><th>4></th></table>	4>
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iter	n	Dimension (mm)					
Dimension	Power	а	b	с	f		
0603	1/20W	0.3	1.1	0.45	5.2		
1005	1/16W	0.6	1.9	0.7	4.9		
1608	1/10W	1.0	3.0	1.2	4.5		
2012	1/8W	1.2	4.0	1.65	4.3		
3216	1/4W	2.2	5.0	2.0	3.3		
3225	1/3W	2.2	5.0	2.9	3.3		
5025	2/3W	3.6	7.0	3.0	3.0		
6432	1W	5.2	8.0	3.5	2.5		



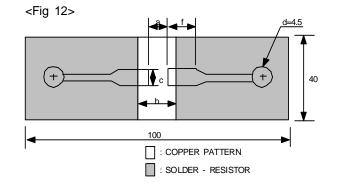
<Table 14>, <Fig 11> are dimensions of test board.

- * Board material : epoxy JIS C 6484
- * pattern material : pure copper 99.5% or above JIS C 6484

▷ Bending Test Board

<table 1<="" th=""><th>5></th></table>	5>
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ite	m	Dimension (mm)				
Dimension	Power	а	b	С	f	
0603	1/20W	0.3	1.1	0.45	5.2	
1005	1/16W	0.6	1.9	0.7	4.9	
1608	1/10W	1.0	3.0	1.2	4.5	
2012	1/8W	1.2	4.0	1.65	4.3	
3216	1/4W	2.2	5.0	2.0	3.3	
3225	1/3W	2.2	5.0	2.9	3.3	
5025	2/3W	3.6	7.0	3.0	3.0	
6432	1W	5.2	8.0	3.5	2.5	



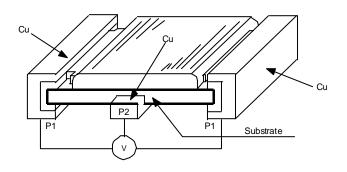
<Table 15>, <Fig 12> are dimensions of bending test board.

* Board material : epoxy JIS C 6484

* pattern material : pure copper 99.5% or above JIS C 6484

Sketch of Withstanding voltage and Insulation resistance

<Fig 13>





PACKAGING

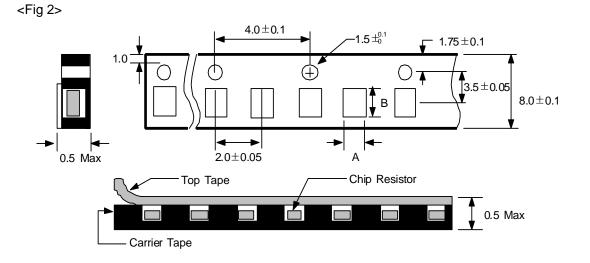
PACKAGING METHOD

Packaging protects the resistor from damage during the shipping or storage. There are two types of packaging method ; one is "Reel" type, and the other is "Bulk" type.

REEL TYPE PACKAGING SPECIFICATION

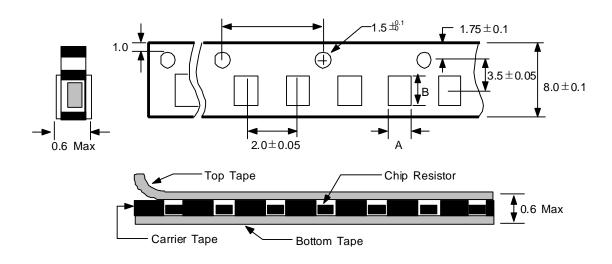
The packaging specification is based on the EIAJ RC-1009.

<Fig 2> is tape dimension For 0603 type. <Table 5> is for pocket sizes, A and B.



<Fig 2-1> is tape dimension For 1005 type. <Table 5> is for pocket sizes, A and B.

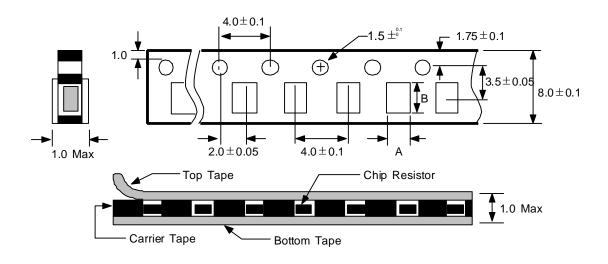
<Fig 2-1>





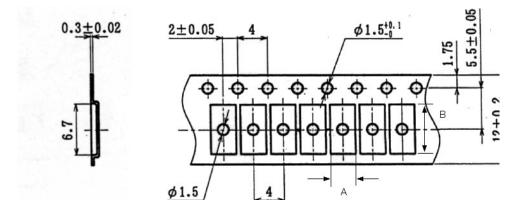
<Fig 3> is tape dimension For 1608, 2012, 3216, 3225 type. <Table 5> is for pocket sizes, A and B.

<Fig 3>



<Fig 4> is tape dimension For 5025, 6432 type. <Table 5> is for pocket sizes, A and B.

<Fig 4>



<Table 5>

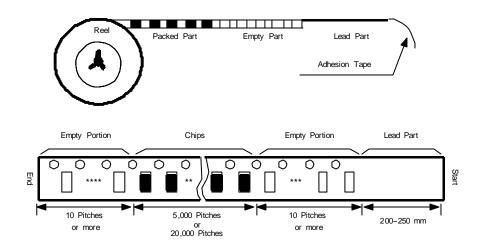
Qimension	0603	1005	1608	2012	3216	3225	5025	6432
Symbol	(0201)	(0402)	(0603)	(0805)	(1206)	(1210)	(2010)	(2512)
А	0.38±0.05	0.70 ± 0.10	1.10 ± 0.20	1.65±0.20	2.00 ± 0.20	2.90 ± 0.20	2.80 ± 0.20	3.50 ± 0.20
В	0.68±0.05	1.20±0.10	1.90±0.20	2.40±0.20	3.60±0.20	3.60±0.20	5.30 ± 0.20	6.75±0.20



TAPING METHOD

There are empty holes at both start part and end part of carrier tape. <Fig 5>

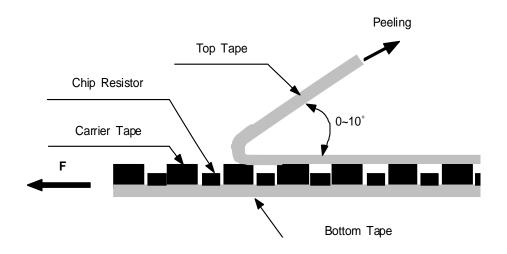
<Fig 5>



Note

- ① The resistor should move in the pocket freely.
- 2 The resistor should not adhere to the top or bottom tape.
- ③ There should be no vacant pocket.
- 4 Peeling strength of the top tape should be within 5gf and 80gf. <Fig 6>



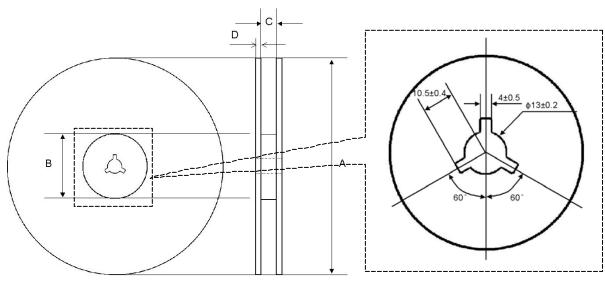




REEL DIMENSION

The Reel dimension is classified by the diameter of Reel. <Fig 7> <Table 6>

<Fig 7>



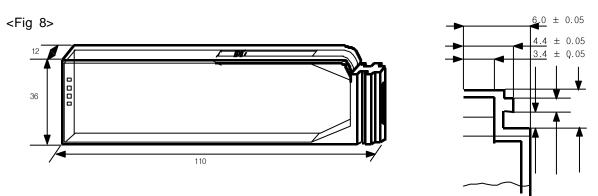
[Unit	:	mm	1
•				

Packaging Code	Diameter	А	В	С	D
C S	7"	178	Φ 60	$9.5(13.0) \pm 0.5$	1.2 ± 0.2
E S	10"	258	Φ 80	9.5 ± 0.5	1.8 ± 0.2
FS, AS	13"	330	Φ 80	$9.5(13.0) \pm 0.5$	2.2 ± 0.2

BULK TYPE PACKAGE

Bulk cassette specification is based on the EIAJ ET-7201. <Fig 8>

The standard packaging quantity depends on the dimension. <Table 7>



<Table 7>

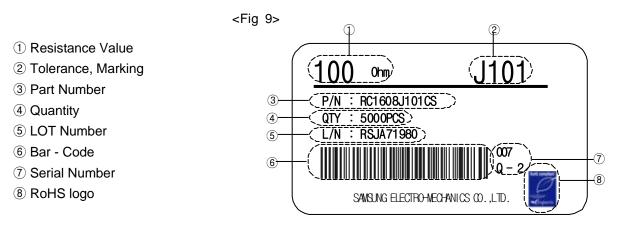
Dimension	Inch	Standard packaging quantity	Weight (g, avg.)
1608	0603	25,000 PCS	71
2012	0805	10,000 PCS	65
3216	1206	5,000 PCS	67



LABELING

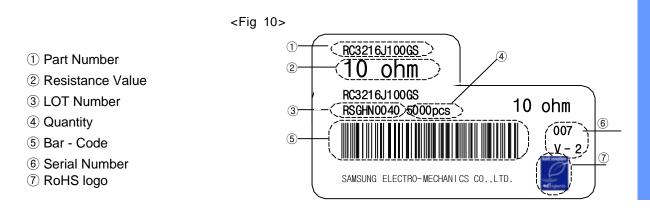
Reel type Label

The reel type label includes the following contents as <Fig 9>.



Bulk type Label

The bulk type label includes following contents as <Fig 10>.



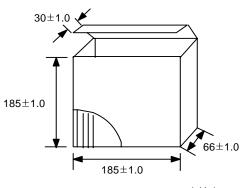
BOX PACKAGING METHOD

- ① The bulk or reel type packaging is packaged twice by paper box, inner box and outer box.
- 2 The packaging should protect the resistor from damage during shipping by land sea or air
- 3 The information of contents is indicated on both inner and outer box.
- * For other packaging methods, please contact us.



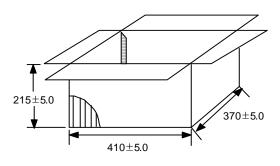
BOX DIMENSION FOR REEL TYPE

1 Max 75,000 pcs (5 EA \times 7")



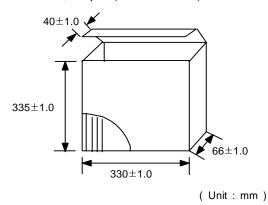
(Unit:mm)

3 Max 900,000 pcs (60 EA $\times 7"$)

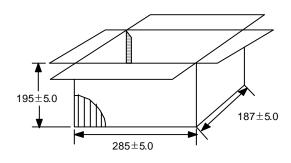


(Unit:mm)

(4) Max 160,000 pcs (4 EA imes 13")

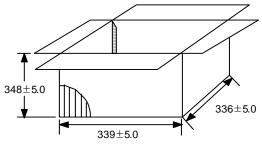


2 Max 300,000 pcs (20 EA \times 7")



(Unit:mm)

 \odot Max 800,000 pcs (20 EA imes13")

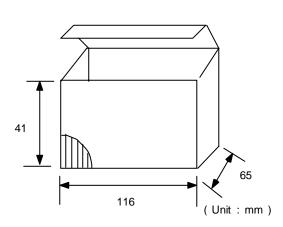


(Unit:mm)

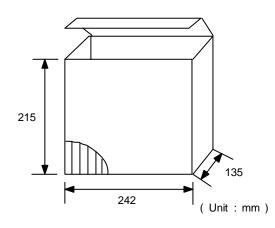


BOX DIMENSION FOR BULK TYPE

1 Inner box (Cassette $\,\times\,$ 5 EA)



2 Outer box (Inner box \times 20 EA)





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APPLICATION MANUAL

APPLICATIONS

Chip resistors are designed for general electronic devices such as home appliances, computer, mobile communications, digital circuit, etc.

If you require our products with high reliability-performing at more than 125C or below -55C for medical equipments, aircraft, high speed machines, military usage, and items that can affect human life or if you need to use in specific conditions (corrosive gas atmosphere), please contact us beforehand.

- ▶ Normal Operation temperature ranges(°C) as follows.
 - 1608, 2012, 3216(general, precision) : -55 °C ~ + 155 °C
 - Others (rectangular, array, trimmable) : -55 $^\circ\!\!\!\!\!\!^\circ$ ~ + 125 $^\circ\!\!\!\!\!^\circ$
- Although resistor body is coated, sharp excessive impact should be avoided to prevent damages and adverse effects on characteristics(resistor value, open circuited, T.C.R.).

STORAGE

To maintain proper quality of chip components, the following precautions are required for storage environment, method and period.

Storage Environment

- Chip components may be deformed, if the temperature of packaged components exceeds 40 $^\circ C$.
- Do not store where the soldering properties can be deteriorated by harmful gas such as sulphurous gas, chlorine gas, etc.
- Bulk packed chip components should be used as soon as the seal is opened, thus preventing the solderability from deteriorating.
- The remaining unused chips should be put in the original bag and sealed again or store in a desiccator containing a desiccating agent.

Storage Time Period

- Stored chip components should be used within 6 months after receiving the components. If 6 months or more have elapsed, please check the solderability before actually using.



MOUNTING

Proper nozzle height must be given attention so as not to give excessive pressure on the chip during mounting on the PCB.

(Excessive pressure may cause exterior damage, change in resistance, circuit open, etc.)

SOLDERING

Our products have Ag electrodes protected by double layer.

- 1st Ni Coating
 - This prevents Ag electrode from leaching and enhance the bonding with Sn

2nd Sn Coating

- This is made of Sn 100% with melting point 232°C to prevent it from melting when solder cream melts, and to enhance the bonding.
- Commercial solder creams are made of Sn-3.0Ag-0.5Cu with melting point 217 °C.

CLEANING

If rosin flux is used, cleaning usually is unnecessary. When strongly activated flux is used, chlorine in the flux may dissolve into some types of cleaning fluids, thereby affecting the chip capacitors. This means that the cleaning fluid must be carefully selected, and should always be new.

• CAUTION FOR CHIP RESISTOR SEPERATION FROM PCB

Chip resistor installation on PCB is similar phenomenon as chocolate chip on top of cake. PCB has enough flexibility on outer force but Chip resistor can be defected without any bending. (By chip resistor use of Ceramic, solder, metal)

Therefore, when separate from Chip resistor on PCB, be ware of any crack of chip

OTHERS

Manual work

Manual soldering can pose a great risk of creating thermal cracks in chip resistors. The hot soldering iron tip comes into direct contact with the end terminations, an operator's carelessness may cause the tip of the soldering iron to come into direct contact with the ceramic body of the resistor.

Therefore the soldering iron must be handled carefully, and close attention must be paid to the selection of the soldering iron tip and to temperature control of the tip.

Do not use more than rated voltage.(check the contents on the file)



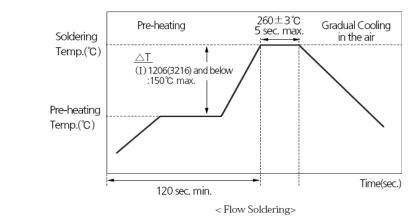
NOTICE

• RECOMMENDED USAGE OF THE RESISTOR

► Flow Soldering

After mounting the resistor to PCB with paste, dip the PCB into solder bath. <Fig 15>

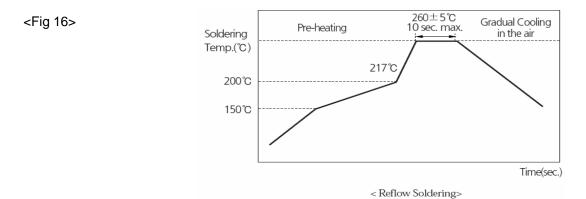
<Fig 15>



Reflow Soldering

After printing solder creams on PCB, place the resistor on the solder cream.

Then heat the PCB. <Fig 16>



CAUTION

Storage condition

Please make sure to keep the storage conditions.

* Temperature : 5 $^\circ C$ \sim 40 $^\circ C$, * Humidity : 20%RH \sim 70%RH

Damage control

Please handle with care to prevent damaging the resistor. Specially, the excessive nozzle height of SMD or the extreme pressure with tweezers.

Leaching prevention

It is important to keep the soldering conditions to prevent Ag leaching in Flow soldering.